Optimized Mobile System Power

"Exact Power @ Exact Time"

PWRSoC 2016

Session 8: Granular Power

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Contents

- Mobile System Contents & Teardown
- System Power and Connectivity
- Power Delivery and Si Technology Trends
- System Power Management & Sequencing
- Putting it altogether!

Typical Smart Phone System Contents

- Apps Processor
 - 14nm Quad-Core
- Graphics Processor
 - Capable of 4K @ 60fps

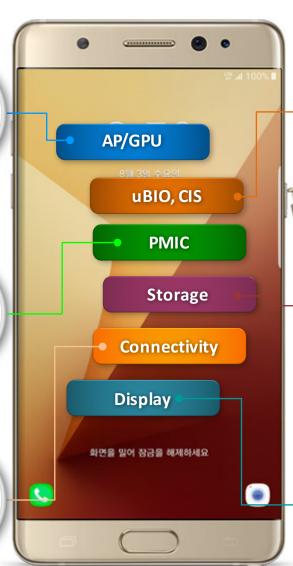


- Power Management
 - PFM/PWM
 - Multi-Phase
 - Thin and Tiny



- Cellular (LTE-A)
- WiFi (802.11abgn)
- BLE-4.1
- GNSS (Quad mode)









- CAM & IRIS Modules
- Bio Sensors



- eMMC
- UFS
- DDR



- AMOLED
- 5.7" QHD (2560x1440)
- RES = 3.7M-pixels

Typical Wearable System Contents

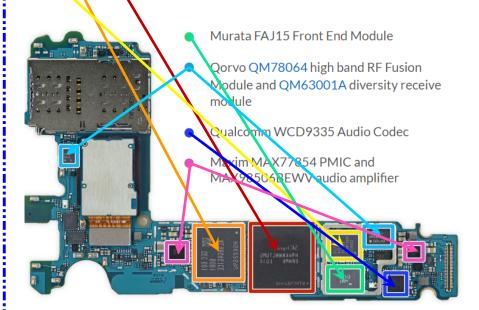


Galaxy S7-Edge Teardown

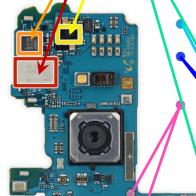
Galaxy S7-Edge Platform Front-Side SK Hynix H9KNNNCTUMU-BRNMH 4 GB LPDDR4 SDRAM layered over the

- Samsung KLUBG4G1CE 32 GB MLC Universal Flash Storage 2.0
- Avago AFEM-9040 Multiband Multimode Module

Qualcomm MSM8996 Snapdragon 820



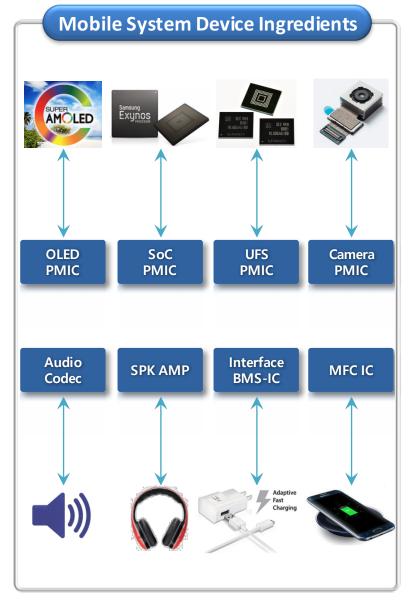
Murata KM5D17074 Wi-Fi module NXP 67T05 NFC Controller IDT P9221 Wireless Power Reciever (likely an iteration of IDT P9220) Qualcomm PM8996 and PM8004 PMICs

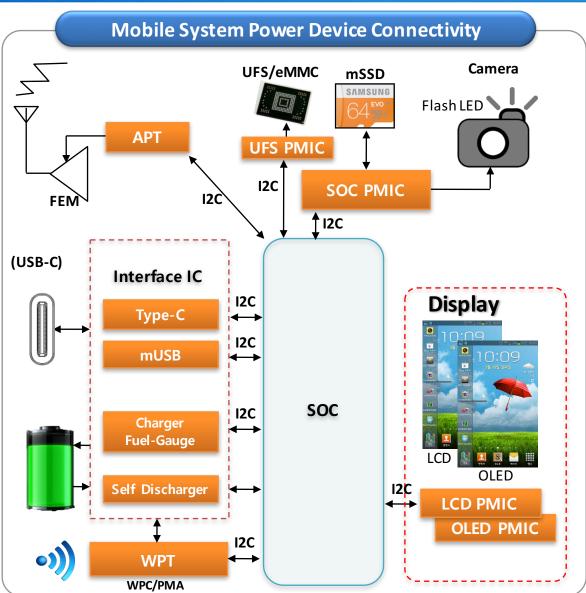


- Qualcomm QFE3100 Envelope Tracker
- Qualcomm WTR4905 and WTR3925 RF Transceivers
- Salveung C3 image processor and Samsung S2M 202 PMIC

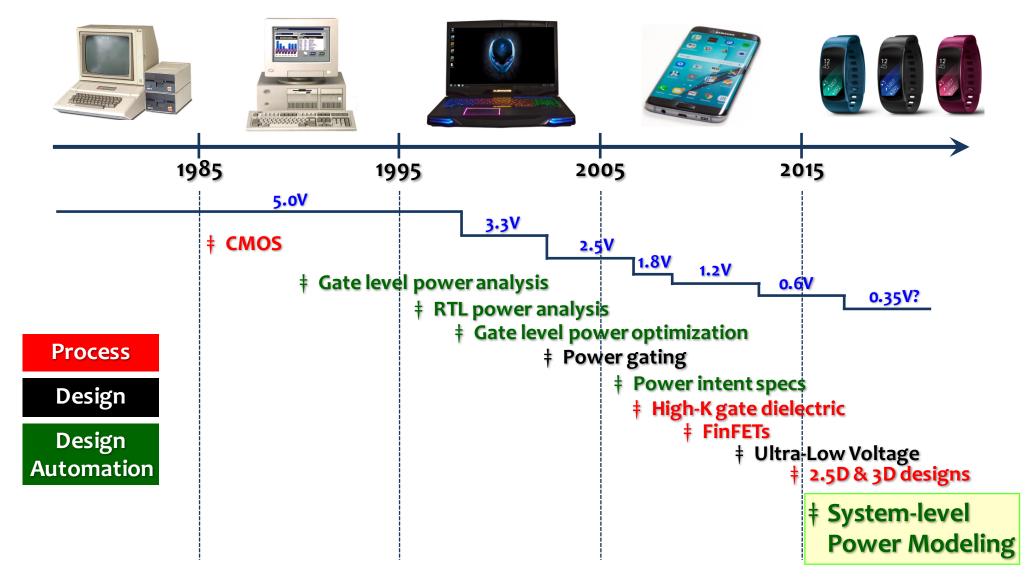
^{*} Courtesy of iFixit

Typical Mobile Device System Power





Silicon Technology Trend Setters



^{*} Courtesy of DAC 2016

Power Delivery Requirements

Not η_{PEAK} , not even η_{MAX} , but W-I-D-E-S-T η_{HIGH} (%) Wins!

Higher Power Requirement -> Complex Power Delivery and Management

Battery Charger







Modem/RF Power



Storage **Power**



Display Power



GPU Power



CPU Power

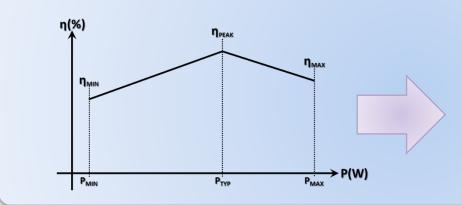


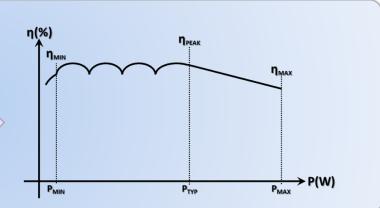
ISP Core-DVS

- Avg. PWR Track
- **ENV.** Tracking
- Dyn. Lane CTRL
- Panel PWR DVS On-Fly On/Off
- **DVFS**
 - **Power Gating**
- **CL-DVFS**
- **Power Gating**
- Auto-CLK

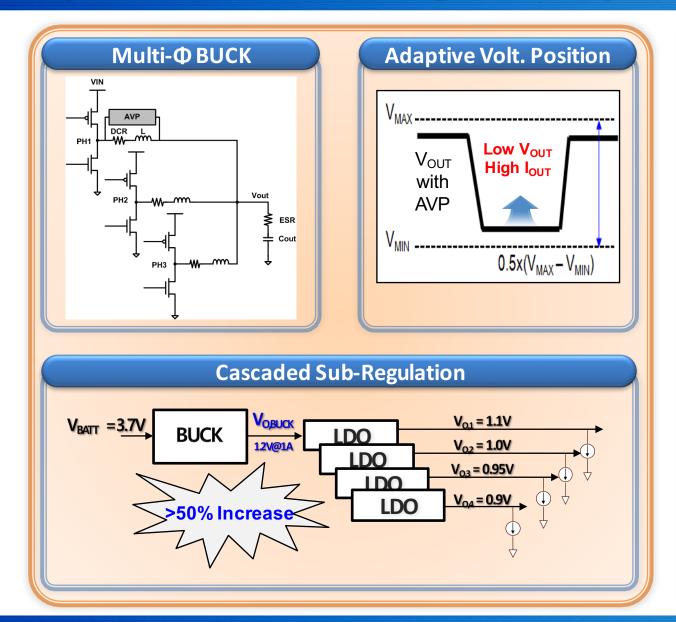


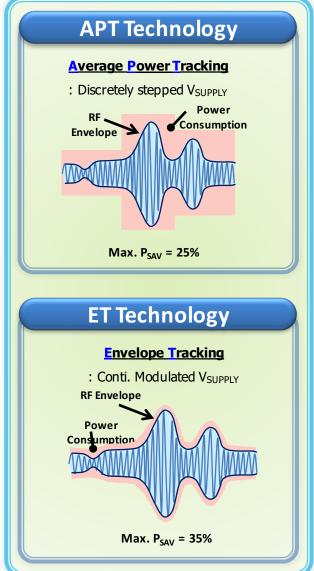




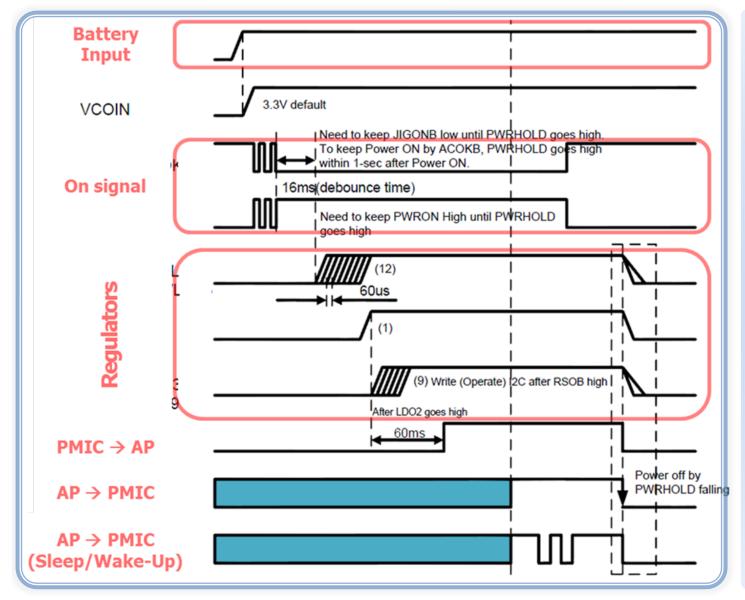


System Power Saving Techniques





Typical Mobile SoC Power Sequencing



Input Power

- → 1-S Li-ion BATT
- → V_{BUS} &/or V_{SYS}

PMIC Enabler

- → Discrete On/Off
- $\rightarrow 1^2C$

VR Sequencer

- → Integrated SEQ
- → By-pass via I²C

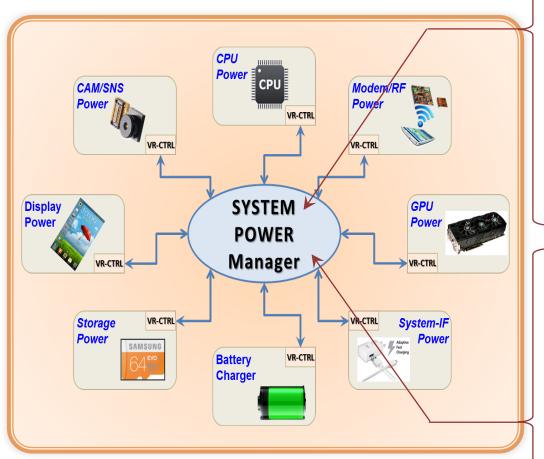
PMIC COM-Link

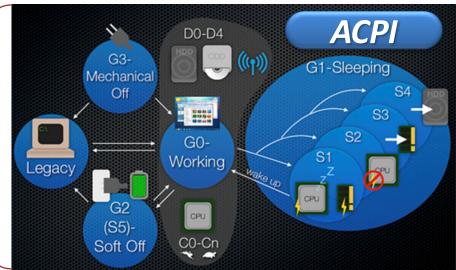
→ Interrupts via I²C

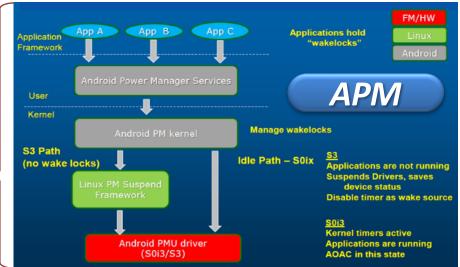
System Power Management Technology

- THERM_THROT: Active Thermal Throttling
 - → Skin Temperature Consideration
 - → System Thermal Throttling
 - → CPU & Device Thermal Throttling
- **SMPL:** Sudden Momentarily Power Loss
 - → Dynamic f_{CLK} Throttling to LFM for System Stability
- **●** P_{MAX}: Maximum Power
- **⊖** P_{LIM}: Power Limiting
- ACPI: Advanced Configuration & Power Interface
 - \rightarrow G-State: G0 \sim G4 // S-State: S0 \sim S4
 - \rightarrow C-State: C0 \sim C6 // P-State: P0 \sim P_n, P_m
 - → D-State: D0 ~ D4
- APM: Android Power Management

Mobile System Power Manager w/ ACPI & APM







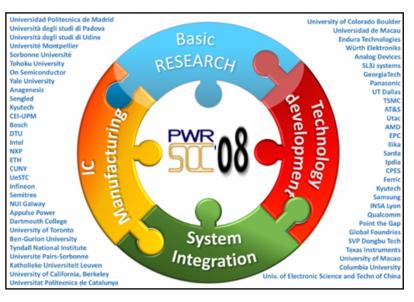
System Power Management

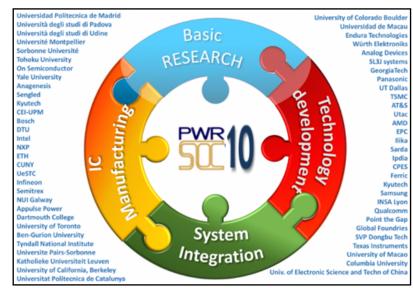
- Mobile System Power trends increase in Complexity
 - → Expect more features/performance with longer battery life
- Advances in System Power Delivery
 - → New advanced technologies for higher and flatter efficiency
- System Power Management
 - → System Power Delivery must be controlled
 - → Aging ACPI and APM...
- Intelligent System Power Management????

Thank you

Backup

Previous PWRSoC Presentations









Packaging Technology

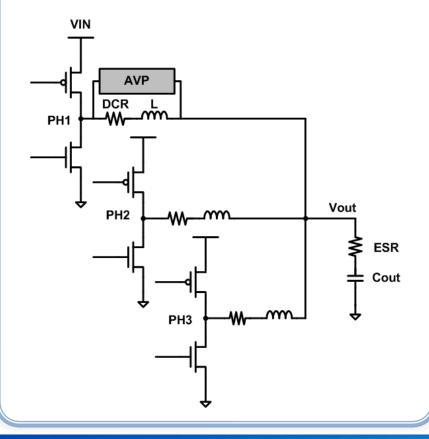
Package Solution	WB_FBGA	QFN_ELP Ag	FC-FBGA (CUF/MUF mini)	WLP
PKG Cost	**	**	*	****
Reliability	****	***	****	****
PKG size (Degree of Freedom)	***	**	***	****
Remark	Popular Packaging Method PKG size limit ; > 3.0x3.0mm² (Die-size Independent) Limitation of Array-type Pad configuration.	- Popular Packaging Method - Quality issue ; PKG crack Issue due to CTE Gap (LF/EMC/EPOXY) - Limitation of Array-type Pad configuration.	- Popular Packaging Method - Cost addition (PCB & Bump)	- PKG size = Chip size - Complicated Process ; WF level EDS/Test Issue (Vertical probing) Ball pitch & Chip size is estimated. Only outsource site.

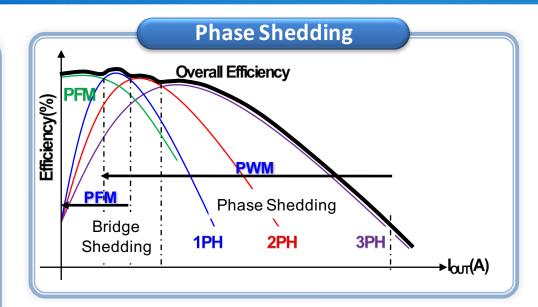
Multi-Phase SMPS for Wide Efficiency Curvature

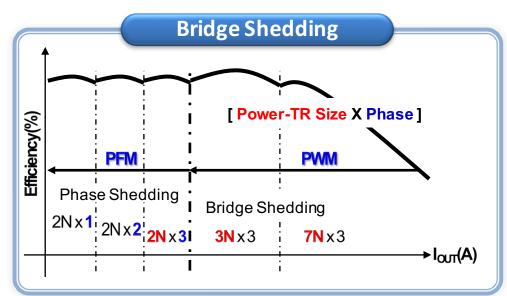
9A, 3- Φ BUCK: $\eta(\%)_{MAX} = 89\%$

Conditions:

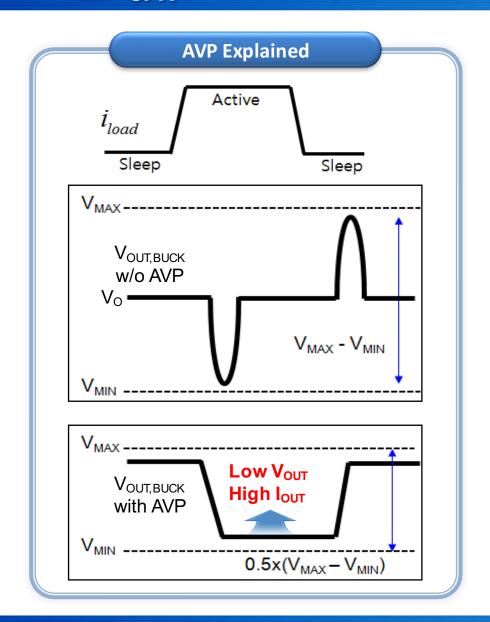
- V_{IN}=3.8V, V_{OUT}=0.9V
- L=0.47uH, C_{IN}=10uF, C_{OUT}=66uF

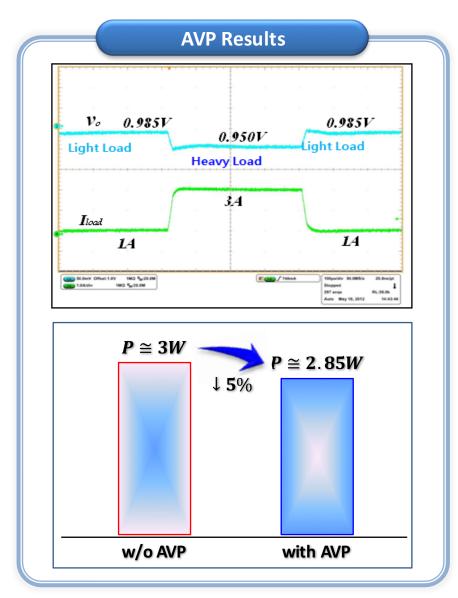




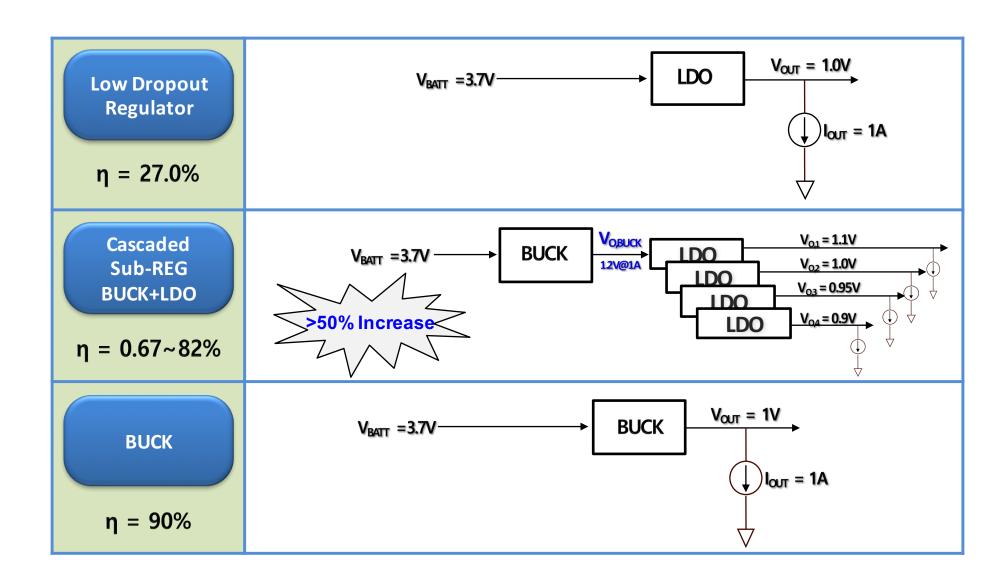


SYS_P_{SAV} Technique: Adaptive Volt Positioning





SYS_P_{SAV} Technique: Cascaded Sub-Regulation



SYS_P_{SAV} Technique: APT & ET for RF

APT & ET Introduction

- → PA's power consumption is at the peak during smart phone wireless transmission.
- → Average Power Tracking and/or Envelope Tracking techniques are used to increase energy efficiency.

Average Power Tracking

→ PA's supply voltage is discretely stepped in order to save power

Envelope Tracking

→ PA's supply voltage is continuously modulated to match envelope to save power

